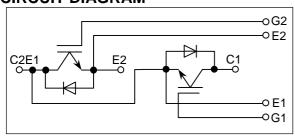
MBM400GR6

[Rated 400A/600V, Dual-pack type]

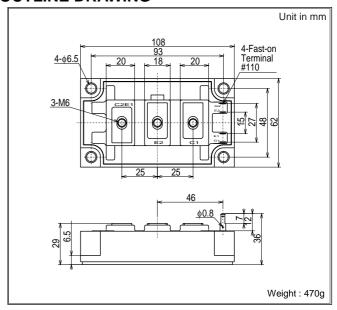
FEATURES

- Low saturation voltage and high speed.
- Low turn-OFF switching loss.
- Low noise due to build-in free-wheeling diode.
 (<u>Ultra Soft and Fast recovery Diode (USFD)</u>)
- High reliability structure.
- Isolated heat sink (terminals to base).

CIRCUIT DIAGRAM



OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS(T_c=25°C)

Item		Symbol	Unit	Value		
Collector-Emitter Voltage		V _{CES}	V	600		
Gate-Emitter Voltage		V_{GES}	V	±20		
Collector Current	DC	I _C	^	400		
	1ms	I _{CP}	A	800		
Forward Current	DC	I _F	^	400 *1		
	1ms	I _{FM}	- A	800		
Collector Power Dissipation		P _c	W	1170		
Junction Temperature		T _i	°C	-40 ~ +150		
Storage Temperature		T _{stg}	°C	-40 ~ +125		
Isolation Voltage		V _{iso}	V_{RMS}	2500(AC 1 minute)		
Screw Torque	Terminals		N⋅m (kgf⋅cm)	2.94(30) *2		
	Mounting	_		2.94(30) *3		

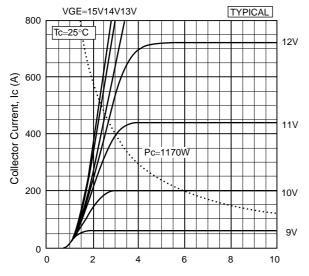
Notes; *1: RMS current of Diode ≤ 120 Arms

CHARACTERISTICS (T_c=25°C)

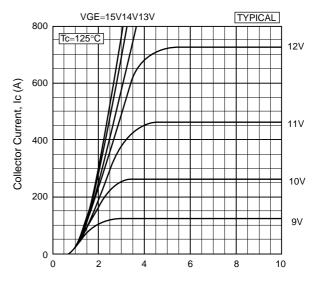
CHARACTERISTICS (T _C =23 C)										
Item		Symbol	Unit	Min.	Тур.	Max.	Test Conditions			
Collector-Emitter Cut-Off Current		I _{CES}	mA	_	_	1.0	V _{CE} =600V, V _{GE} =0V			
Gate-Emitter Leakage Current		I _{GES}	nA	_	_	±500	$V_{GE}=\pm 20V, V_{CE}=0V$			
Collector-Emitter Saturation Voltage		V _{CE(sat)}	V	_	2.1	2.6	I _C =400A, V _{GE} =15V			
Gate-Emitter Threshold Voltage		V _{GE(TO)}	V	_	_	10	V _{CE} =5V, I _C =400mA			
Input Capacitance		C _{ies}	pF	_	20000	_	V _{CE} =10V, V _{GE} =0V, f=1MHz			
Switching Times	Rise Time	t _r	μ\$	_	0.25	0.5	V _{cc} =300V			
	Turn-ON Time	t _{on}		_	0.35	0.7	$R_L=0.75\Omega$			
	Fall Time	t _f		_	0.2	0.32	$R_G=6.2\Omega$ *4			
	Turn-Off Time	t _{off}		_	0.8	1.1	V _{GE} =±15V			
Peak Forward Voltage Drop		V_{FM}	V	_	1.6	2.2	I _F =400A, V _{GE} =0V			
Reverse Recovery Time		t _{rr}	μS	_	_	0.3	I _F =400A, V _{GE} =-10V,di/dt=400A/μs			
Thermal Impedance	IGBT	R _{th(j-c)}	°C/W	ı	ı	0.106	Junction to case			
	FWD	R _{th(j-c)}				0.22				

Notes; *4:R_G value is the test condition's value for decision of the switching times, not recommended value, please determine the suitable R_G value after the measurement of switching waveforms (overshoot voltage, etc.) with appliance mounted. Remark; The specification given herein, is subject to change without prior notice to improve product characteristics.

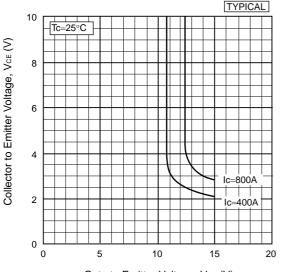
^{*2, *3 :} Recommended value 2.45 N·m (25 kgf·cm)



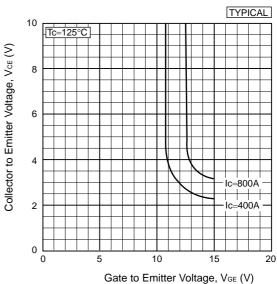
Collector to Emitter Voltage, VcE (V)
Collector current vs. Collector to Emitter voltage



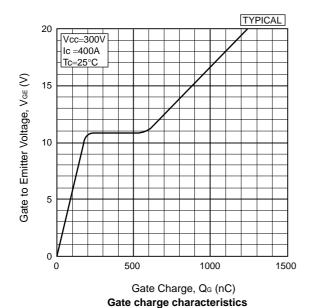
 $\label{eq:collector} \text{Collector to Emitter Voltage, V}_{\text{CE}} \left(V \right)$ Collector current vs. Collector to Emitter voltage

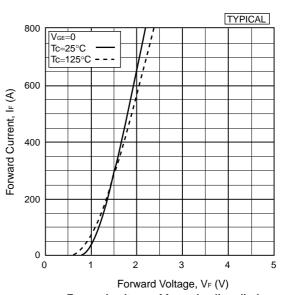


 $\label{eq:Gate to Emitter Voltage, VGE} Gate to Emitter voltage vs. Gate to Emitter voltage$

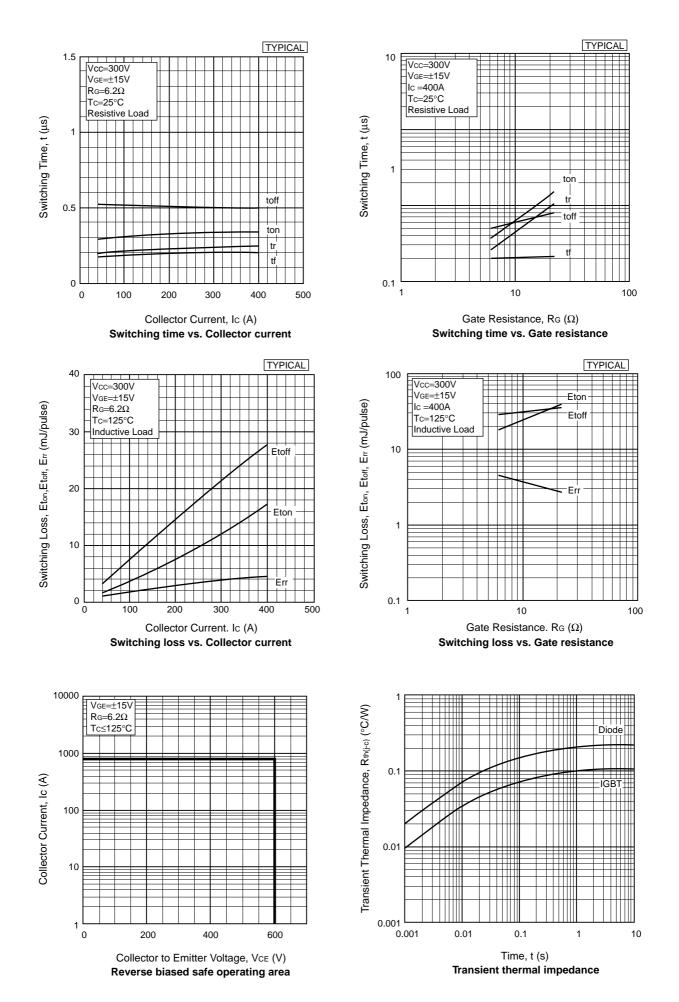


Collector to Emitter voltage vs. Gate to Emitter voltage





Forward voltage of free-wheeling diode



HITACHI POWER SEMICONDUCTORS

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